19-1963; Rev 0; 2/01

EVALUATION KIT AVAILABLE

MAXIM

16:1 Serializer, 3.3V, 2.5Gbps, SDH/SONET, with Clock Synthesis and LVPECL Inputs

General Description

The MAX3891 serializer converts 16-bit wide, 155Mbps parallel data to 2.5Gbps serial data in ATM and SDH/SONET applications. The MAX3891 is ideal for interfacing with high-speed digital circuitry. This device accepts single-ended LVPECL data inputs and delivers differential LVPECL data and clock outputs. An internal 2.5Gbps serial clock, synthesized by a fully integrated PLL that accepts multiple input reference clock rates, retimes the output data stream. The MAX3891 operates from a single +3.3V supply and accepts differential LVPECL reference clock rates of 155.52MHz, 77.76MHz, 51.84MHz, or 38.88MHz. A CML loopback data output is provided to facilitate system diagnostic testing. The MAX3891 is available in the extended temperature range (-40°C to +85°C) in a 64-pin TQFP exposed pad (EP) package.

Applications

2.5Gbps SDH/SONET Transmission Systems

2.5Gbps Access Nodes

Add/Drop Multiplexers

Digital Cross-Connects

ATM Backplanes

Features

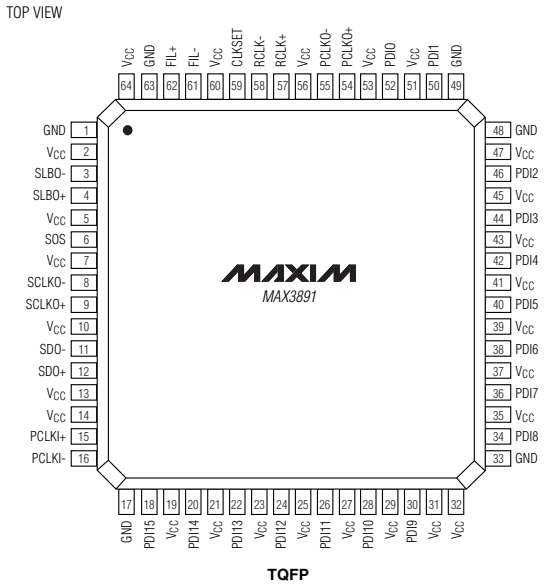
- **Single +3.3V Supply**
- **495mW Power Consumption**
- **Exceeds ANSI, ITU, and Bellcore Specifications**
- **155Mbps (16-bit wide) Parallel to 2.5Gbps Serial Conversion**
- **Clock Synthesis for 2.5Gbps**
- **Multiple Clock Reference Frequencies (155.52MHz, 77.76MHz, 51.84MHz, 38.88MHz)**
- **Additional High-Speed Output for System Loopback Testing**
- **Single-Ended PECL Data Inputs**
- **Differential PECL Clock Inputs and Serial Data Outputs**

Ordering Information

PART	TEMP. RANGE	PIN-PACKAGE
MAX3891ECB	-40°C to +85°C	64 TQFP EP*

**EP = Exposed Pad*

Pin Configuration



Typical Application Circuit appears at end of data sheet.

For price, delivery, and to place orders, please contact Maxim Distribution at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

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ABSOLUTE MAXIMUM RATINGS

Terminal Voltage (with respect to GND)
- V_{CC} .....-0.5V to +5.0V
- All Inputs, FIL+, FIL- .....-0.5V to (V_{CC} + 0.5V)

Output Currents
- PECL Outputs (SDO±, SCLKO±, PCLKO±) 50mA
- CML Outputs (SLBO±).....15mA

Continuous Power Dissipation (T_A = +85°C)
- 64-Pin TQFP-EP (derate 45.5mW/°C above +85°C) 2.9W

Operating Temperature Range .....-40°C to +85°C
Storage Temperature Range .....-60°C to +150°C
Lead Temperature (soldering, 10s) .....+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

(V_{CC} = +3.0V to +3.6V, PECL loads = 50Ω ±1% to (V_{CC} - 2V), CML loads = 50Ω ±1% to V_{CC}, T_A = -40°C to +85°C. Typical values are at V_{CC} = +3.3V and T_A = +25°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Supply Current	I_{CC}	PECL outputs unterminated, SOS = iow		150	230	mA
PECL OUTPUTS (SDO±, SCLKO±, PCLKO±)						
Output Voltage High	V_{OH}	T_A = 0°C to +85°C	V_{CC} - 1.025		V_{CC} - 0.88	V
		T_A = -40°C	V_{CC} - 1.085		V_{CC} - 0.88	
Output Voltage Low	V_{OL}	T_A = 0°C to +85°C	V_{CC} - 1.81		V_{CC} - 1.62	V
		T_A = -40°C	V_{CC} - 1.83		V_{CC} - 1.555	
PECL INPUTS (PDI_, PCLKI±, RCLK±)						
Input High Voltage	V_{IH}		V_{CC} - 1.16		V_{CC} - 0.88	V
Input Low Voltage	V_{IL}		V_{CC} - 1.81		V_{CC} - 1.48	V
Input Current High PDI_, RCLKI±	I_{IH}		-10		+10	µA
Input Current Low PDI_, RCLKI±	I_{IL}		-10		+10	µA
Input Current High PCLKI±	I_{IH}		-60		+60	µA
Input Current Low PCLKI±	I_{IL}		-60		+60	µA
PROGRAMMING INPUT (CLKSET)						
CLKSET Input Current	I_{CLKSET}	CLKSET = GND or V_{CC}			±500	µA
TTL INPUT (SOS)						
TTL Input High Voltage	V_{IH}		2.0			V
TTL Input Low Voltage	V_{IL}				0.8	V
TTL Input High Current	I_{IH}		-10		+10	µA
TTL Input Low Current	I_{IL}		-10		+10	µA
CURRENT MODE LOGIC (CML) OUTPUTS (SLBO±)						
CML Differential Output Voltage Swing	$\|V_{OD}\|$	R_L = 50 Ω to V_{CC}	100		400	mV
CML Single-Ended Output Impedance	R_O			50		Ω

AC ELECTRICAL CHARACTERISTICS

(V_{CC} = +3.0V to +3.6V, PECL loads = 50Ω ±1% to (V_{CC} - 2V), CML loads = 50Ω ±1% to V_{CC}, T_A = -40°C to +85°C. Typical values are at T_A = +25°C and V_{CC} = +3.3V, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Serial Clock Rate	f_{SCLK}			2.488		GHz
Parallel Data Setup Time	t_{SU}	(Notes 2, 3)	300			ps
Parallel Data-Hold Time	t_H	(Notes 2, 3)	700			ps
PCLKO to PCLKI Skew	t_{SKEW}	Figure 1	0		+4.0	ns
Output Jitter Generation (SCLKO±)		Jitter bandwidth = 12kHz to 20MHz			3	ps_{RMS}
PECL Differential Output (SDO±, SCLKO±) Rise/Fall Time	t_R, t_F	20% to 80%			120	ps
Parallel Input Clock Rate	f_{PCLKI}			155.52		MHz
Reference Clock Input (RCLK±) Rise/Fall Time	t_R, t_F	20% to 80%, f = 155.52MHz			1.0	ns
Parallel Clock Output (PCLKO±) Rise/Fall Time	t_R, t_F	20% to 80%			1.0	ns
Serial-Clock Output (SCLKO±) to Serial-Data Output (SDO±) Delay	$t_{SCLK-SD}$	SCLKO rising edge to SDO edge	110		290	ps

Note 1: AC characteristics are guaranteed by design and characterization.

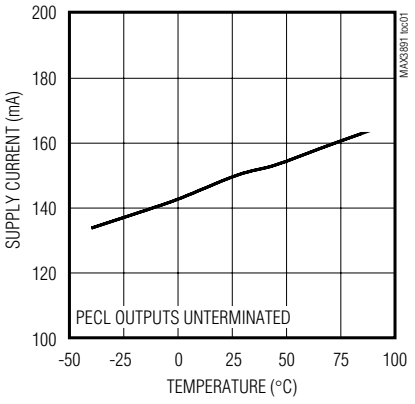
Note 2: Setup and hold times are relative to the rising edge of PCLKI+, measured by applying a 155.52MHz differential parallel clock with rise/fall time = 1ns (20% to 80%). See Figure 1.

Note 3: Setup and hold time measurements assume that the PCLKI and PDI signals are from the same source and have identical common-mode voltages, swings, and slew rates.

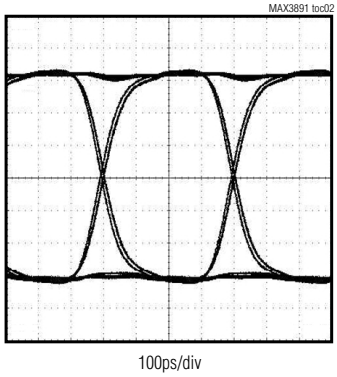
Typical Operating Characteristics

(V_{CC} = +3.3V, T_A = +25°C, unless otherwise noted.)

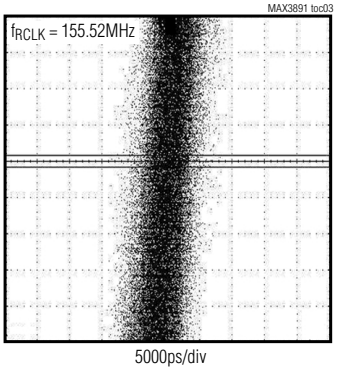
SUPPLY CURRENT vs. TEMPERATURE



SERIAL-DATA OUTPUT EYE DIAGRAM



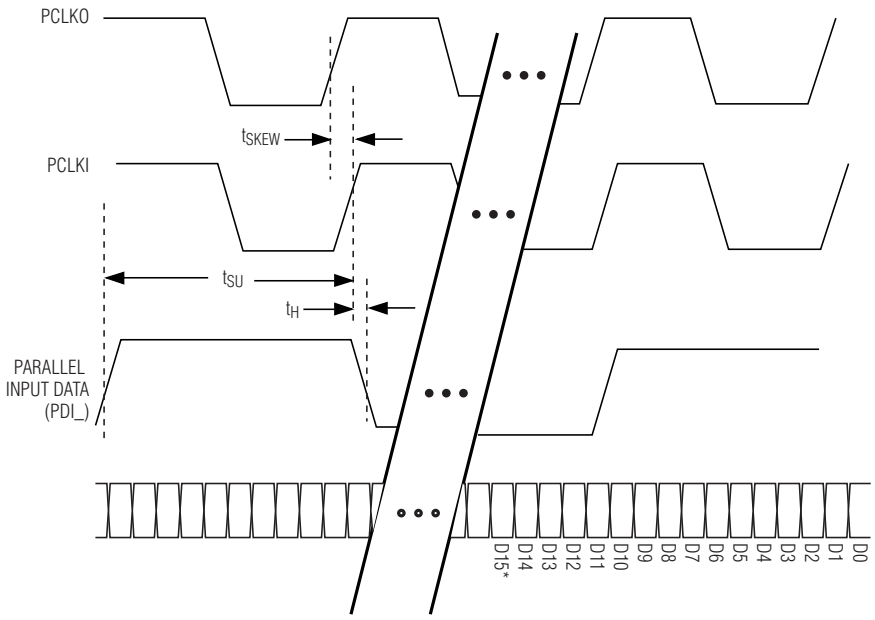
SERIAL-DATA OUTPUT JITTER



16:1 Serializer,3.3V, 2.5Gbps, SDH/SONET, with Clock Synthesis and LVPECL Inputs

Pin Description

PIN	NAME	FUNCTION
1, 17, 33, 48, 49, 63	GND	Ground
2, 5, 7, 10, 13, 14, 19, 21, 23, 25, 27, 29, 31, 32, 35, 37, 39, 41, 43, 45, 47, 51, 53, 56, 60, 64	V_{CC}	+3.3V Supply Voltage
3	SLBO-	System Loopback Negative Output. Enabled when SOS is high.
4	SLBO+	System Loopback Positive Output. Enabled when SOS is high.
6	SOS	System Loopback Output Select, TTL Input. System loopback disabled when low.
8	SCLKO-	Negative PECL Serial Clock Output
9	SCLKO+	Positive PECL Serial Clock Output
11	SDO-	Negative PECL Serial Data Output
12	SDO+	Positive PECL Serial Data Output
15	PCLKI+	Positive PECL Parallel Clock Input. Connect the incoming parallel-clock signal to the PCLKI inputs. Note that data is updated on the positive transition of the PCLKI signal.
16	PCLKI-	Negative PECL Parallel Clock Input. Connect the incoming parallel-clock signal to the PCLKI inputs. Note that data is updated on the positive transition of the PCLKI signal.
18, 20, 22, 24, 26, 28, 30, 34, 36, 38, 40, 42, 44, 46, 50, 52	PDI15 to PDI0	Single-Ended PECL Parallel Data Inputs. Data is clocked on the PCLKI positive transition. PDI15 is transmitted first.
54	PCLKO+	Positive PECL Parallel Clock Output. Use positive transition of PCLKO to clock the overhead management circuit.
55	PCLKO-	Negative PECL Parallel Clock Output. Use positive transition of PCLKO to clock the overhead management circuit.
57	RCLK+	Positive Reference Clock Input. Connect a PECL-compatible crystal reference clock to the RCLK inputs.
58	RCLK-	Negative Reference Clock Input. Connect a PECL-compatible crystal reference clock to the RCLK inputs.
59	CLKSET	Reference Clock Rate Programming Pin: CLKSET = V_{CC}: Reference Clock Rate = 155.52MHz CLKSET = Open: Reference Clock Rate = 77.76MHz CLKSET = 20kΩ to GND: Reference Clock Rate = 51.84MHz CLKSET = GND: Reference Clock Rate = 38.88MHz
61	FIL-	Filter Capacitor Input. Connect a 0.33µF capacitor between FIL+ and FIL-
62	FIL+	Filter Capacitor Input. Connect a 0.33µF capacitor between FIL+ and FIL-
EP	Exposed Pad	Ground. This must be soldered to a circuit board for proper electrical and thermal performance (see exposed pad package information).



NOTE: SIGNALS SHOWN ARE DIFFERENTIAL. FOR EXAMPLE, PCKLO = (PCLK0+) - (PCLKO-).
*PDI I5 = D15; PDI14 = D14, . . . PDI0 = D0.
THIS FIGURE IS NOT INTENDED TO SHOW A SPECIFIC TIMING RELATIONSHIP BETWEEN PARALLEL INPUT DATA AND SERIAL OUTPUT DATA.

Figure 1. Timing Diagram

Detailed Description

The MAX3891 converts 16-bit wide, 155Mbps data to 2.5Gbps serial data (Figure 2). The MAX3891 is composed of a 16-bit parallel input register, a 16-bit shift register, control and timing logic, PECL output buffers and a frequency-synthesizing PLL, consisting of a phase/frequency detector, loop filter/amplifier, voltage-controlled oscillator, and prescaler.

The PLL synthesizes an internal 2.5Gbps reference used to clock the output shift register. This clock is generated from the external 155.52MHz, 77.76MHz, 51.84MHz, or 38.88MHz reference-clock signal (RCLK).

The incoming parallel data is clocked into the MAX3891 on the rising transition of the parallel clock-input signal (PCLKI). Proper operation is ensured if the parallel-input register is latched within a window of time (t_{SKEW}), defined with respect to the parallel clock-output signal (PCLKO). PCLKO is the synthesized 2.488Gbps internal serial-clock signal divided by 16. The allowable PCLKO to PCLKI skew is 0ns to 4ns. This defines a timing window after the PCLKO rising edge, during which a PCLKI rising edge may occur (Figure 1).

System Loopback

The MAX3891 is designed to provide system loopback testing. The loopback outputs (SLBO) of the MAX3891 may be directly connected to the loopback inputs of a deserializer (MAX3881) for system diagnostics. To enable the SLBO outputs, apply a TTL logic-high signal to the SOS input. The same signal that controls the SOS enable input may also be used to control the SIS enable input on the MAX3881.

16:1 Serializer,3.3V, 2.5Gbps, SDH/SONET, with Clock Synthesis and LVPECL Inputs

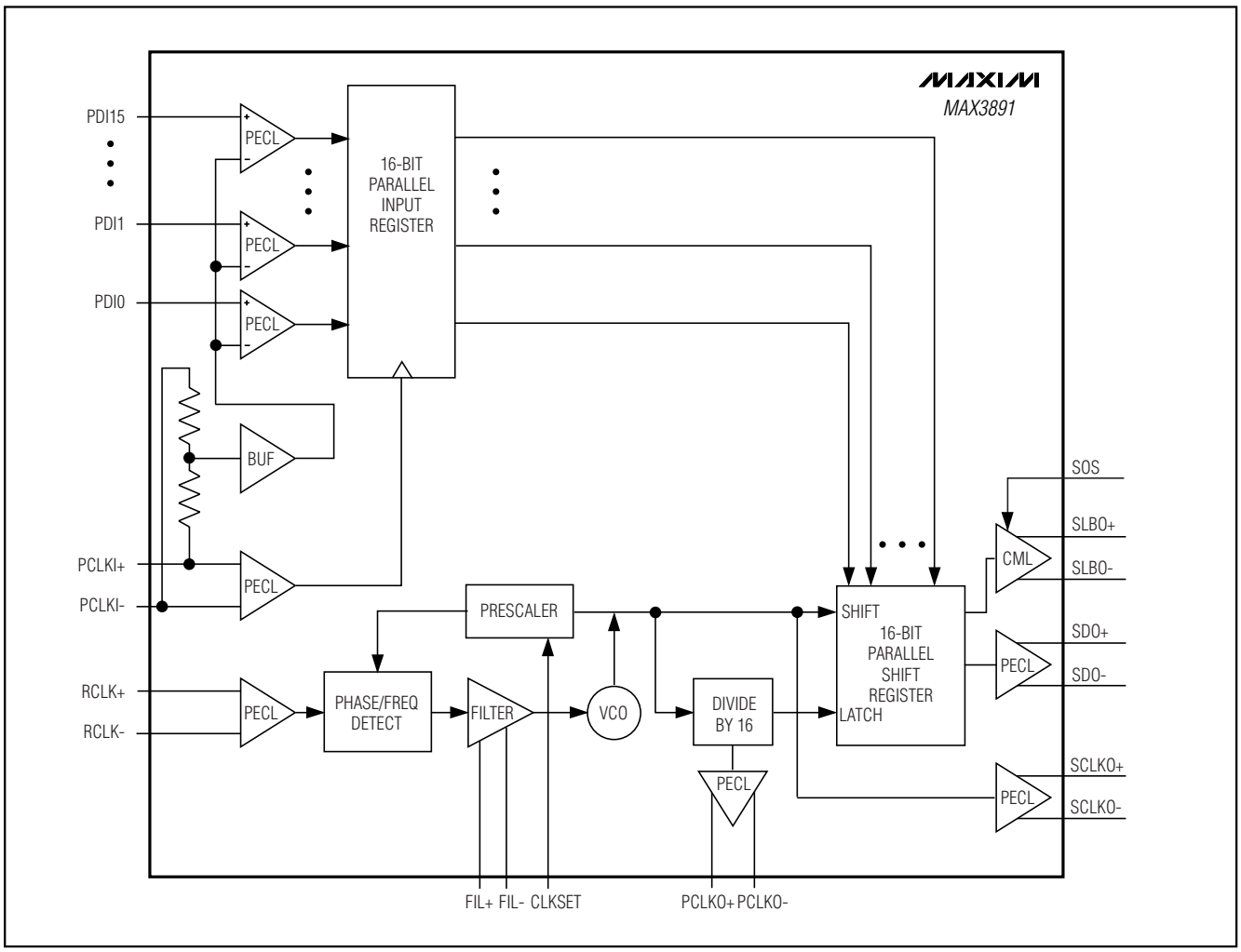


Figure 2. Functional Block Diagram

Applications Information

Setup and Hold Time Requirements

The setup and hold-time specifications assume that the parallel clock-input signal (PCLKI) and parallel-data input signal (PDI_) are from the same source. They should have identical common-mode voltages, signal amplitudes, and slew rates. If PCLKI and PDI_ differ significantly, the setup and hold-time requirements must be modified to account for these differences. Define t_{DEG} as the adjustment to the setup and hold-time requirement when there are significant differences between PCLKI and PDI_.

$$t_{DEG} = VCM_{DIFF} \times \frac{t_T}{\left(\frac{0.6}{V_{OH} - V_{OL}}\right)}$$

where t_T is the transition time (20%–80%) of the parallel-data and clock-input signals, V_{OH} and V_{OL} are the input high and low voltage, respectively, of the parallel-data and clock-input signals, and VCM_{DIFF} is the difference in common-mode voltages of the parallel-data and clock-input signals.

The adjusted setup (t_{SUADJ}) and hold-time (t_{HADJ}) requirements become

$$t_{SUADJ} \text{ (or } t_{HADJ}) = t_{SU} \text{ (or } t_H) + t_{DEG}$$

PECL Input and Output Terminations

It is important to bias the MAX3891's PECL data and clock IOs appropriately. Figures 3 and 4 show alternative PECL output termination methods. A circuit that provides 50Ω to (V_{CC} - 2V) should be used in conjunction with controlled impedance transmission lines for proper termination. Use Thevenin equivalent termination when a (V_{CC} - 2V) supply is not available. If AC-coupling is necessary, make sure that the coupling capacitor follows the 50Ω or Thevenin equivalent DC termination. To ensure best performance, the differential outputs (SDO± and PCLKO±) must have balanced loads.

Current-Mode Logic Outputs

The system loopback outputs (SLBO) of the MAX3891 are CML compatible. The configuration of the MAX3891 current-mode logic (CML) output circuit includes internal 50Ω back termination to V_{CC} (Figure 5). These outputs are intended to drive a terminated 50Ω transmission line.

Layout Techniques

For best performance, use good high-frequency layout techniques. Filter voltage supplies and keep ground connections short. Use multiple vias where possible. Use controlled impedance transmission lines to interface with the MAX3891 clock and data inputs and outputs.

Exposed Pad Package

The 64-pin exposed pad (EP) TQFP incorporates features that provide a very low thermal-resistance path for heat removal. The MAX3891 EP must be soldered directly to a ground plane with good thermal conductance.

Chip Information

TRANSISTOR COUNT: 1712

PROCESS: Bipolar

16:1 Serializer,3.3V, 2.5Gbps, SDH/SONET, with Clock Synthesis and LVPECL Inputs

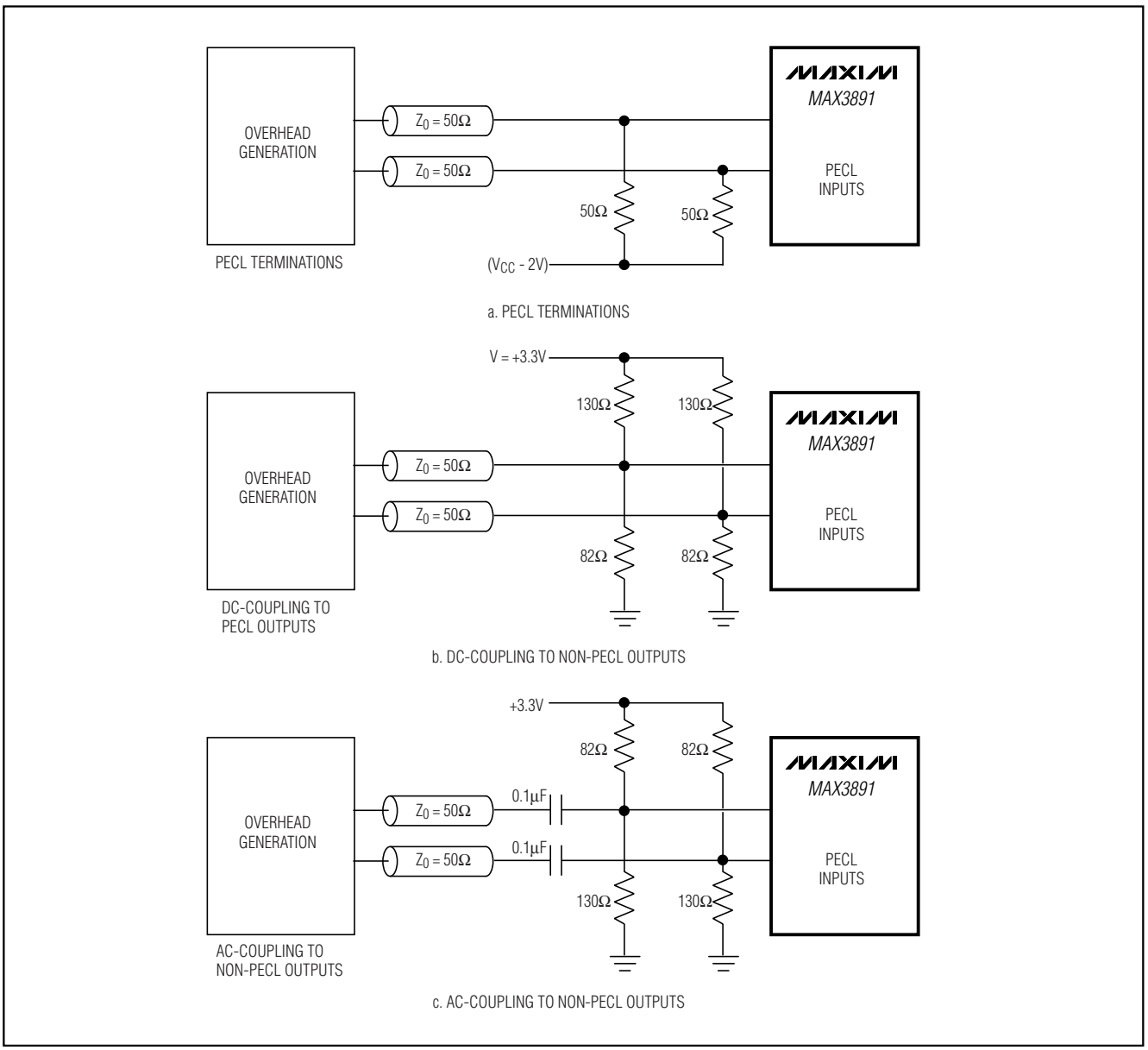


Figure 3. Alternative PECL-Input Termination

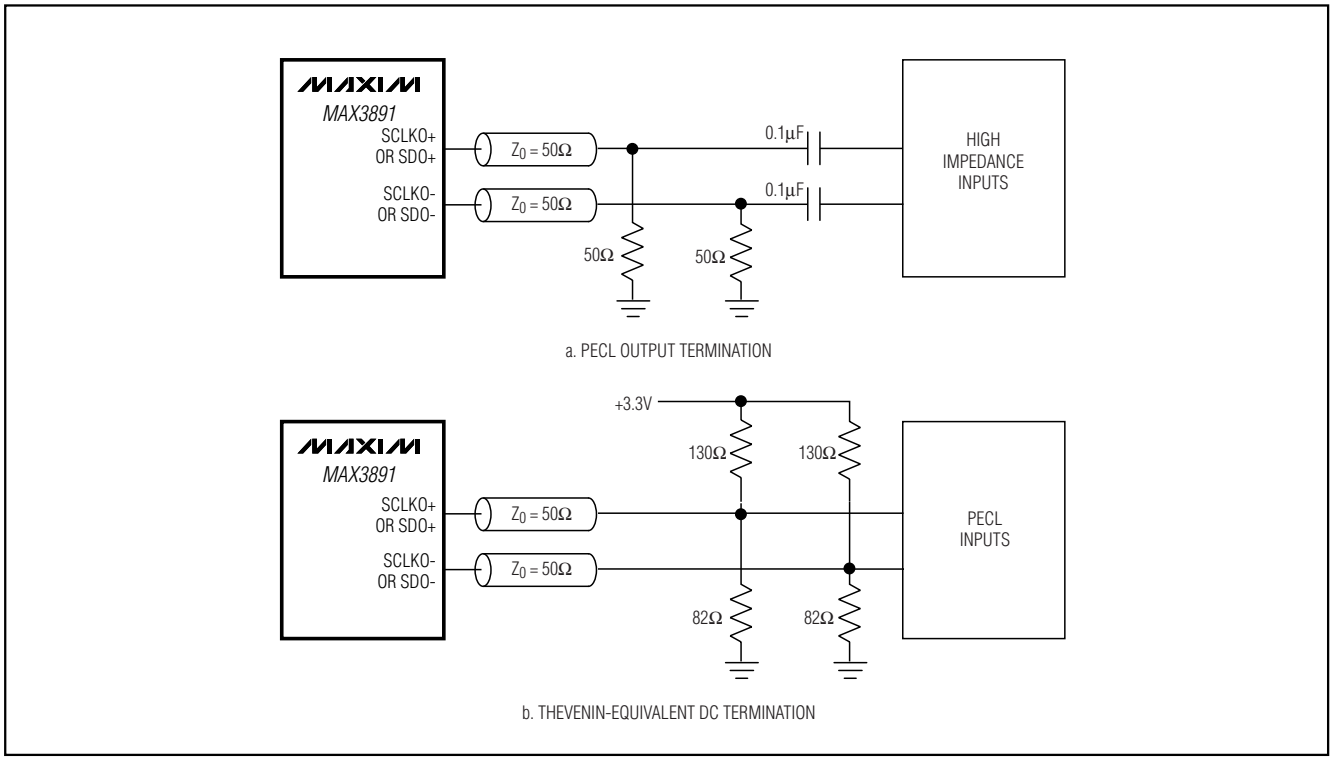


Figure 4. Alternative PECL-Output Termination

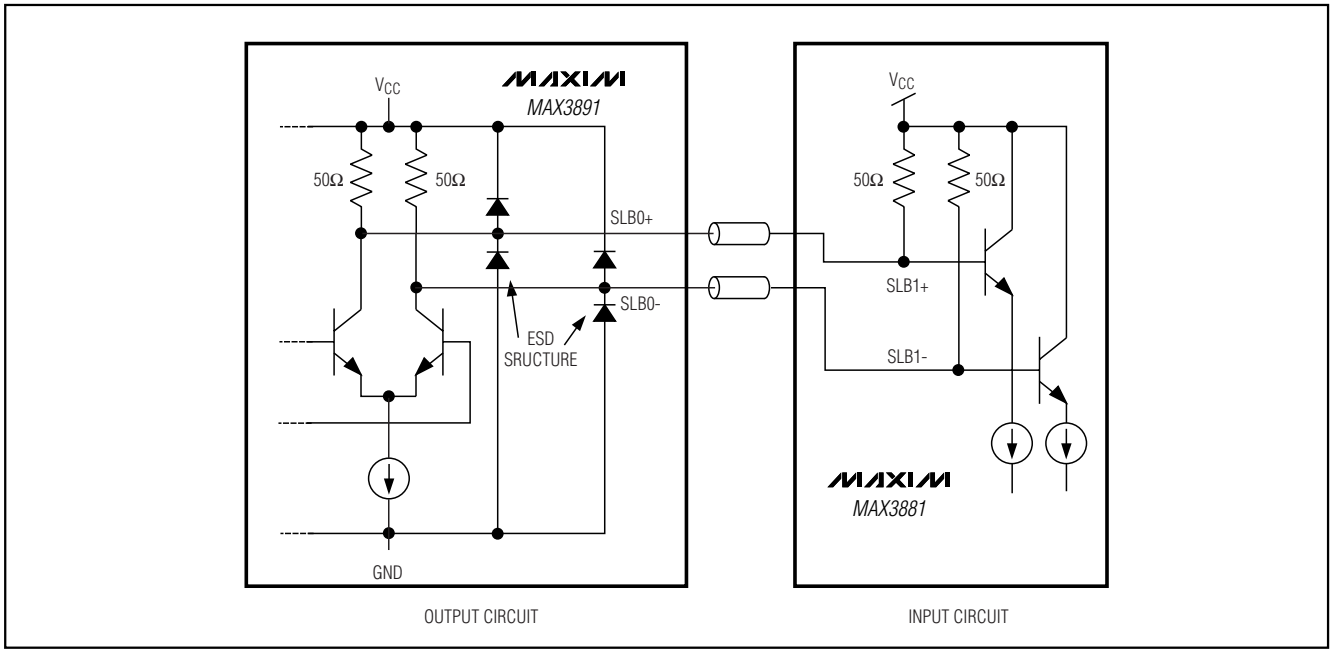
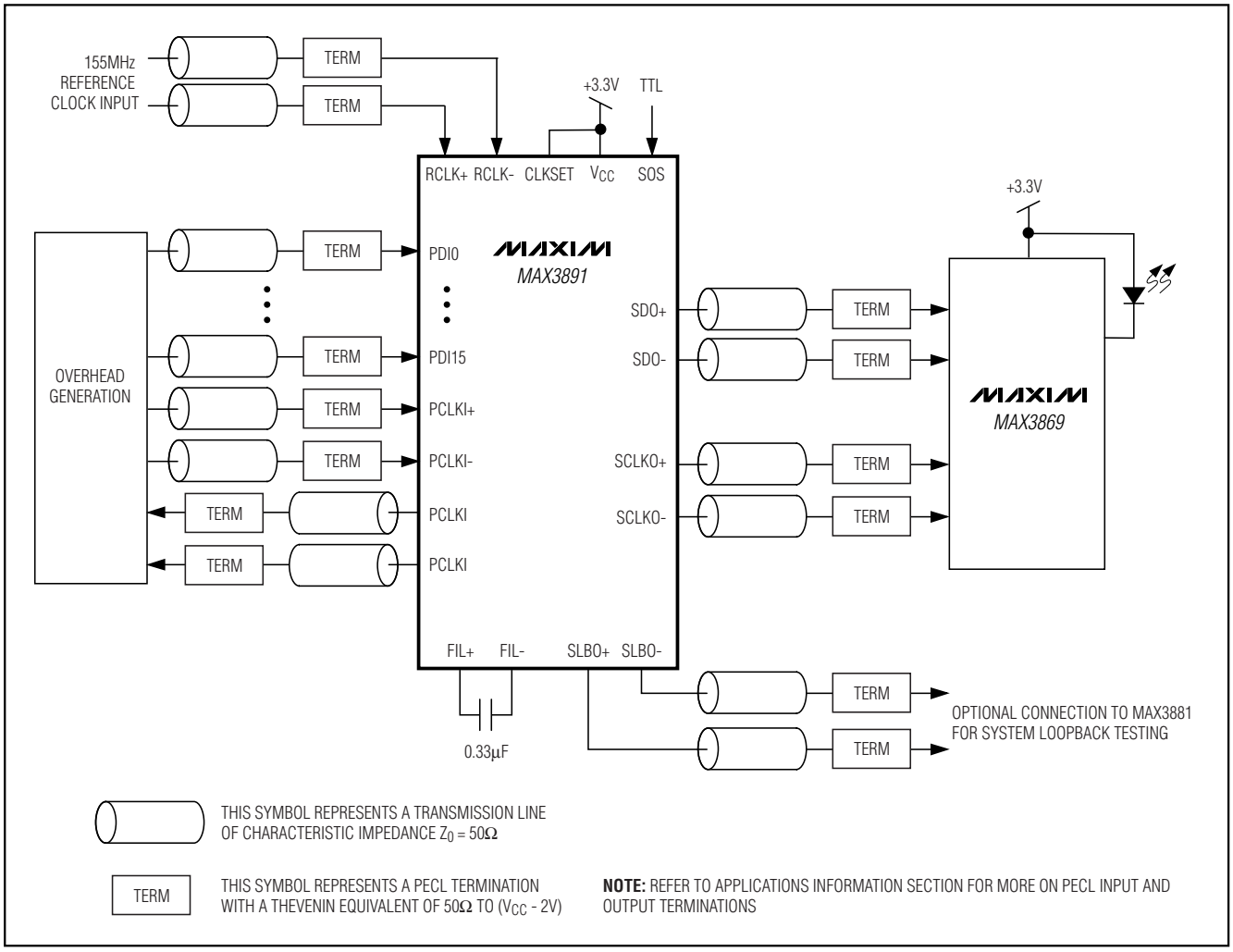


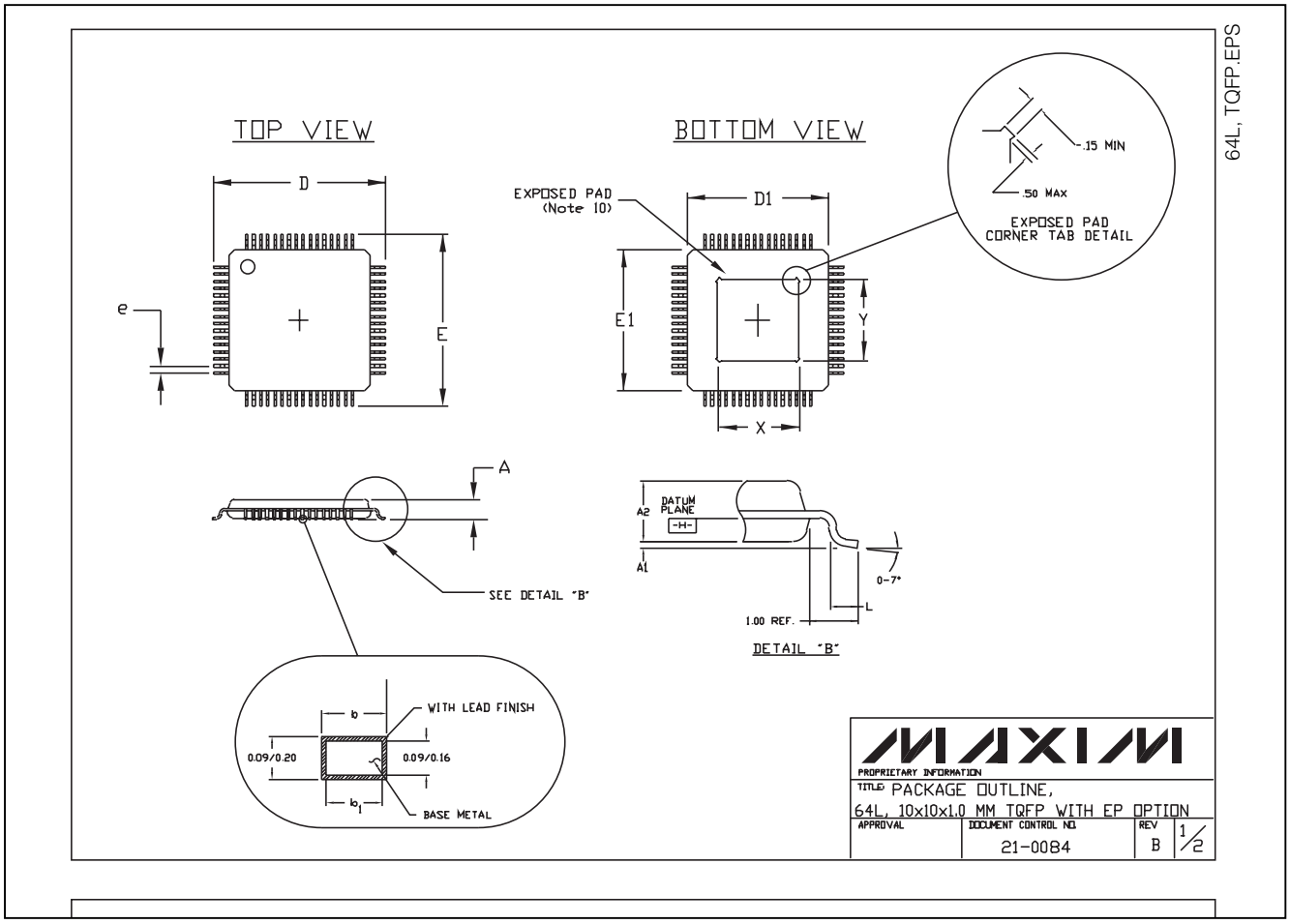
Figure 5. Current-Mode Logic

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Typical Application Circuit



Package Information



16:1 Serializer,3.3V, 2.5Gbps, SDH/SONET, with Clock Synthesis and LVPECL Inputs

Package Information (continued)

NOTES:
1. ALL DIMENSIONS AND TOLERANCING CONFORM TO ANSI Y14.5-1982.
2. DATUM PLANE -H- IS LOCATED AT MOLD PARTING LINE AND COINCIDENT WITH LEAD, WHERE LEAD EXITS PLASTIC BODY AT BOTTOM OF PARTING LINE.
3. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
4. THE TOP OF PACKAGE IS SMALLER THAN THE BOTTOM OF PACKAGE BY 0.15 MILLIMETERS.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 MM TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. CONTROLLING DIMENSION: MILLIMETER.
7. THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-136, VARIATION AJ.
8. LEADS SHALL BE COPLANAR WITHIN .004 INCH.
9. EXPOSED DIE PAD SHALL BE COPLANAR WITH BOTTOM OF PACKAGE WITHIN 2 MILS (.05 MM).
10. DIMENSIONS X & Y APPLY TO EXPOSED PAD (EP) VERSIONS ONLY. SEE INDIVIDUAL PRODUCT DATASHEET TO DETERMINE IF A PRODUCT USES EXPOSED PAD PACKAGE.

SYMBOL	JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS	
	AJ	
	MIN.	MAX.
A	—	1.20
A_1	0.05	0.15
A_2	0.95	1.05
D	12.00 BSC.	
D_1	10.00 BSC.	
E	12.00 BSC.	
E_1	10.00 BSC.	
L	0.45	0.75
N	64	
e	0.50 BSC.	
b	0.17	0.27
b1	0.17	0.23
*X	4.7	5.30
*Y	4.70	5.30

* EXPOSED PAD (Note 10)

MAXIM
PROPRIETARY INFORMATION
TITLE: PACKAGE OUTLINE, 64L, 10x10x1.0 MM TQFP WITH EP OPTION
APPROVAL | DOCUMENT CONTROL NO. 21-0084 | REV B | 2/2

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